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- (71) Applicant (for all designated States except US): SHOWA DENKO K.K. [JP/JP]; 13-9, Shiba Daimon 1-chome, Mi-

- (74) Agent: OHIE, Kunihisa; Ohie Patent Office. Sclva-Ningyosho 6F, 14-6, Nihonbashi-Ningyocho, 2-chome, Chuo-Ku, Tokyo 103-0013 (JP).
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(72) Inventors; and
(75) Inventors/Applicants (for US only): NAITO, Kazuml [JP/JP]; c/o Corporate R & D Center, Showa Denko K.K.
1-1, Ohnodai 1-chome, Midori-ku, Chiba-shi, Chiba 267-0056 (JP). YABE, Sholj [JP/JP]; c/o Corporate R & D Center, Showa Denko K.K.
Chiba-shi, Chiba 267-0056 (JP). YABE, Sholj [JP/JP]; c/o Corporate R & D Center, Midori-ku, Chiba-shi, electric layer, and an electrically conducting layer stacked on the semiconductor layer, and the solid electrolytic capacitor element is molded with a resin, cured and then applied voltage (aging) treatment, which method comprises sequentially repeating a step of leaving the resin-molded body to stand at 225 to 305°C and a step of aging it twice or more after the steps of molding with resin and curing.